

CELCON® GC25A

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Celcon® acetal copolymer grade GC25A is a glass coupled formulation containing 25% reinforced fiber glass. This grade offers excellent strength, stiffness and heat distortion temperature with lower mold shrinkage, minimum thermal expansion, excellent dimensional stability and good moldability.

Chemical abbreviation according to ISO 1043-1: POM

Product information

Resin Identification	POM-GF25	ISO 1043
Part Marking Code	>POM-GF25<	ISO 11469

Rheological properties

Moulding shrinkage, parallel	0.6 %	ISO 294-4, 2577
Moulding shrinkage, normal	1.4 %	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	8800 MPa	ISO 527-1/-2
Tensile stress at break, 5mm/min	110 MPa	ISO 527-1/-2
Tensile strain at break, 5mm/min	2.2 %	ISO 527-1/-2
Flexural modulus	8900 MPa	ISO 178
Flexural strength	160 MPa	ISO 178
Charpy impact strength, 23°C	30 kJ/m ²	ISO 179/1eU
Charpy impact strength, -30°C	35 kJ/m ²	ISO 179/1eU
Charpy notched impact strength, 23°C	6.4 kJ/m ²	ISO 179/1eA
Izod notched impact strength, 23°C	6 kJ/m ²	ISO 180/1A
Izod impact strength, 23°C	101 kJ/m ²	ISO 180/1U
Izod impact strength, -40°C	4 kJ/m ²	ISO 180/1U
Poisson's ratio	0.42	

Thermal properties

Melting temperature, 10°C/min	166 °C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	160 °C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	25 E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	120 E-6/K	ISO 11359-1/-2

Flammability

Oxygen index	15.6 %	ISO 4589-1/-2
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Electrical properties

Surface resistivity	3.8E16 Ohm	IEC 62631-3-2
Arc Resistance	136 s	UL 746B

Physical/Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	0.8 %	Sim. to ISO 62
Water absorption, Immersion 24h	0.2 %	Sim. to ISO 62
Density	1580 kg/m ³	ISO 1183

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Injection

Drying Recommended	no
Drying Temperature	100 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	≤0.2 %
Melt Temperature Optimum	190 °C
Min. melt temperature	180 °C
Max. melt temperature	200 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	105 °C
Min. mould temperature	90 °C
Max. mould temperature	120 °C
Hold pressure range	60 - 120 MPa
Back pressure	2 MPa

Characteristics

Additives

Release agent

Additional information

Injection molding

Preprocessing

Drying is generally not required because Celcon materials are not hygroscopic nor are they degraded by moisture during processing. Excessive moisture can lead to splay (silver streaking) in molded parts. For better uniformity in molding especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 80 C (180 F) for three hours. Desiccant hopper dryers are not required. Max. water content = 0.35%.

Processing

Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (i.e.- general purpose 2:1 compression ratio) can result in unmelted particles and poor melt homogeneity. Using a high back pressure to make up for a low compression ratio may lead to excessive shear heating and deterioration of the Celcon material.

Melt temperature: preferred range 182-199 C (360-390 F) Melt temperature should never exceed 230 C (450 F). Mold surface temperature: preferred range 93-121 C (200-250 F) especially with wall thickness less than 1.5 mm (0.060 in.). May require mold temperature as high as 120 C (250 F) to reproduce mold surface or to assure minimal molded in stress. Wall thickness greater than 3 mm (1/8 in.) may use a cooler (65 C/150 F) mold surface temperature and wall thickness over 6 mm (1/4 in.) may use a cold mold surface down to 25 C (80 F). In general, mold surface temperatures lower than 82 C (180 F) may produce a hazy surface or a surface with flow lines, pits and other included defects.

Postprocessing

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Postprocessing conditioning and moisturizing not required. It may be necessary to fixture large or complicated parts with varying wall thickness to prevent warpage while cooling to ambient temperature.

Other extrusion

Preprocessing

Drying is generally not required because Celcon materials are not hygroscopic nor are they degraded by moisture during processing. Excessive moisture can cause surface defects. For better uniformity especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying is 3 hours at 80 C (180 F). Desiccant hopper dryers are not required. Max. moisture content = 0.35%

Processing

Standard extruders with a length to diameter ratio of at least 20:1 are recommended. The screw should be a high compression ratio of at least 3:1 and preferably 4:1 to assure good melting and uniform melt homogeneity. The design should be approximately 35% each for the feed and metering sections with the remaining 30% as transition zone.

Melt temperature 180-220 C (355-430F)

Postprocessing

Postprocessing conditioning or moisturizing are not required. For thick walled sections (>3mm or 1/8 in.), annealing is recommended to reduce internal stresses.

Annealing temperature: 130-140 C (265-285 F)

Annealing time: 10 min/mm thickness

Processing Notes

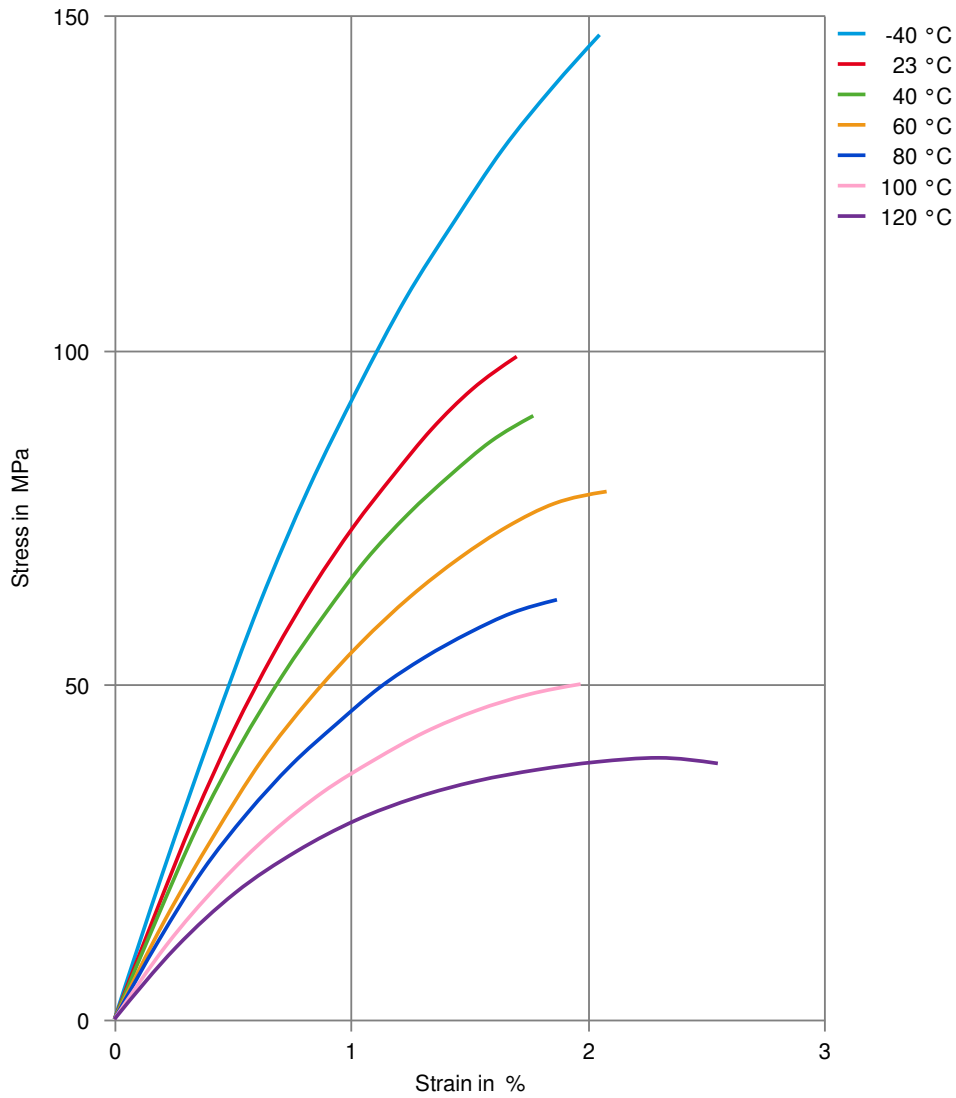
Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

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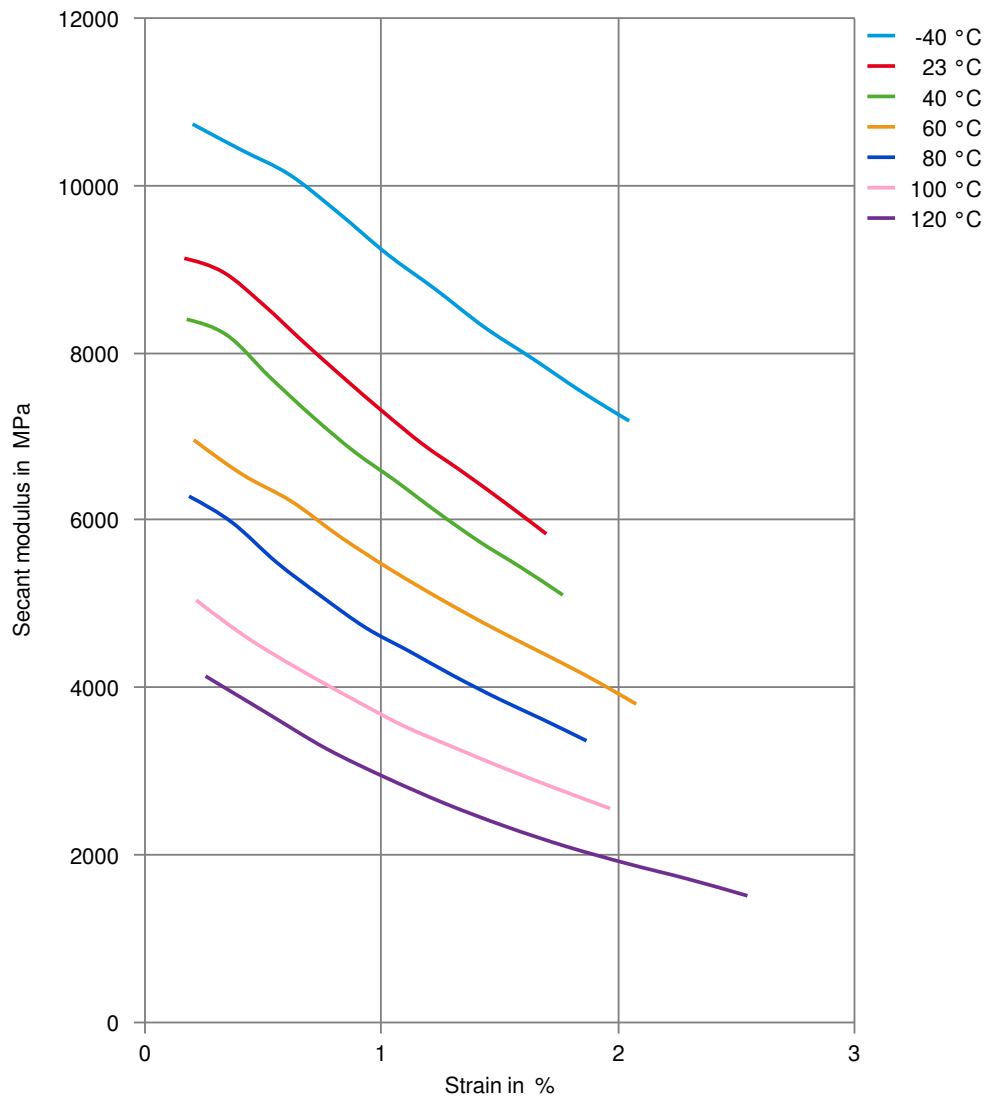
Stress-strain



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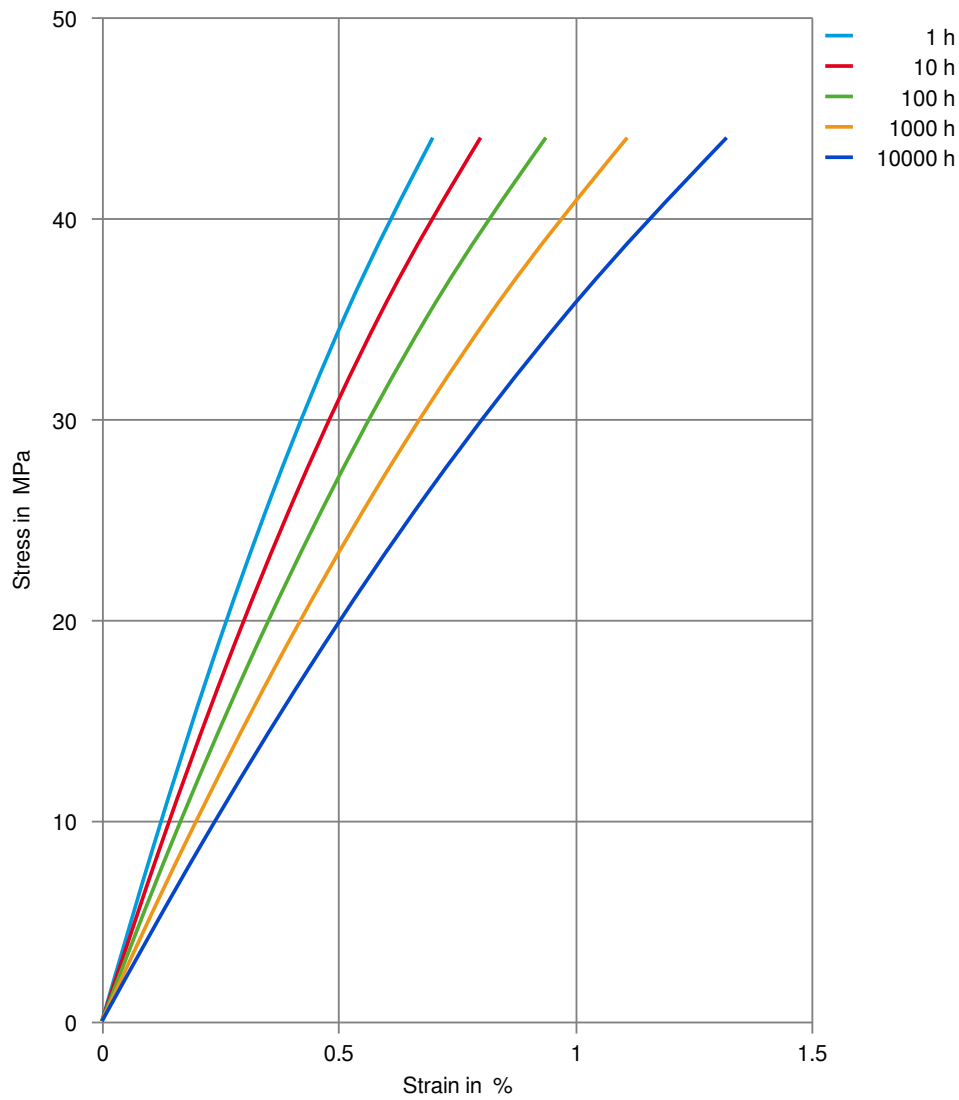
Secant modulus-strain



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Stress-strain (isochronous) 40°C



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Creep modulus-time 40 °C

